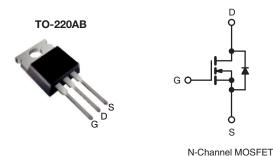


Vishay Siliconix

D Series Power MOSFET

PRODUCT SUMMARY				
V_{DS} (V) at T_J max.	550			
R _{DS(on)} max. at 25 °C (Ω)	$V_{GS} = 10 V$	0.85		
Q _g (max.) (nC)	30			
Q _{gs} (nC)	4			
Q _{gd} (nC)	7			
Configuration	Single			



FEATURES

- Optimal Design
 - Low Area Specific On-Resistance
 - Low Input Capacitance (Ciss)
 - Reduced Capacitive Switching Losses
 - High Body Diode Ruggedness
 - Avalanche Energy Rated (UIS)
- Optimal Efficiency and Operation
 - Low Cost
 - Simple Gate Drive Circuitry
 - Low Figure-of-Merit (FOM): Ron x Qa
 - Fast Switching
- Material categorization: For definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Consumer Electronics
 - Displays (LCD or Plasma TV)
- Server and Telecom Power Supplies
 - SMPS
- Industrial
 Welding
 - Induction Heating
 - Motor Drives
- Battery Chargers

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	SiHP8N50D-E3
Lead (Pb)-free and Halogen-free	SiHP8N50D-GE3

ABSOLUTE MAXIMUM RATINGS ($T_C = 25 \degree C$, unless otherwise noted)						
PARAMETER		SYMBOL	LIMIT	UNIT		
Drain-Source Voltage		V _{DS}	500			
Gate-Source Voltage		N	± 30	V		
Gate-Source Voltage AC (f > 1 Hz)	V _{GS}	30				
Continuous Drain Current (T _J = 150 °C)	V_{GS} at 10 V $T_C = 25 \degree C$		8.7	A		
	V_{GS} at 10 V $T_C = 100 ^{\circ}C$	I _D	5.5			
Pulsed Drain Current ^a	I _{DM}	18				
Linear Derating Factor			1.25	W/°C		
Single Pulse Avalanche Energy ^b		E _{AS}	29	mJ		
Maximum Power Dissipation		PD	156	W		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to + 150	°C		
Drain-Source Voltage Slope	T _J = 125 °C	d)//dt	24			
Reverse Diode dV/dt ^d		dV/dt	0.37	V/ns		
Soldering Recommendations (Peak Temperature) ^c	for 10 s		300	°C		

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature.

b. V_{DD} = 50 V, starting T_J = 25 °C, L = 2.3 mH, R_g = 25 Ω , I_{AS} = 5 Å.

c. 1.6 mm from case.

d. $I_{SD} \leq I_D$, starting $T_J = 25$ °C.

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THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R _{thJA}	-	62	°C/W	
Maximum Junction-to-Case (Drain)	R _{thJC}	_	0.8	0/W	

PARAMETER	SYMBOL	TES	TEST CONDITIONS		TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_D = 250 \mu A$		500	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	Reference to 25 °C, $I_D = 250 \ \mu A$		0.58	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	: V _{GS} , I _D = 250 μA	3	-	5	V
Gate-Source Leakage	I _{GSS}	,	$V_{GS} = \pm 30 \text{ V}$	-	-	± 100	nA
Zava Cata Vialtaga Dirain Current		V _{DS} =	= 500 V, V _{GS} = 0 V	-	-	1	μA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 400 V	', V _{GS} = 0 V, T _J = 125 °C	-	-	10	
Drain-Source On-State Resistance	R _{DS(on)}	$V_{GS} = 10 V$	$I_D = 4 A$	-	0.70	0.85	Ω
Forward Transconductance ^a	9 _{fs}	V _{DS}	= 20 V, I _D = 4 A	-	3	-	S
Dynamic		•					
Input Capacitance	C _{iss}	$V_{GS} = 0 V,$		-	527	-	-
Output Capacitance	C _{oss}	,	$V_{\rm DS} = 0.0$ V, $V_{\rm DS} = 100$ V,		52	-	
Reverse Transfer Capacitance	C _{rss}	f = 1 MHz		-	8	-	
Effective Output Capacitance, Energy Related ^b	C _{o(er)}	$V_{DS} = 0 V$ to 400 V, $V_{GS} = 0 V$		-	46	-	pF
Effective Output Capacitance, Time Related ^c	C _{o(tr)}			-	64	-	
Total Gate Charge	Qg			-	15	30	
Gate-Source Charge	Q _{gs}	$V_{GS} = 10 V$	$I_{D} = 4 \text{ A}, V_{DS} = 400 \text{ V}$	-	4	-	nC
Gate-Drain Charge	Q _{gd}			-	7	-	
Turn-On Delay Time	t _{d(on)}			-	13	26	
Rise Time	t _r	V _{DD}	$V_{DD} = 400 \text{ V}, \text{ I}_D = 4 \text{ A}$ $R_g = 9.1 \Omega, V_{GS} = 10 \text{ V}$		16	32	
Turn-Off Delay Time	t _{d(off)}	$R_g =$			17	34	ns
Fall Time	t _f			-	11	22	
Gate Input Resistance	Rg	f = 1 MHz, open drain		-	1.8	-	Ω
Drain-Source Body Diode Characteristic	s			•	•		•
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	8	
Pulsed Diode Forward Current	I _{SM}			_	-	32	A
Diode Forward Voltage	V _{SD}	T _J = 25 °C, I _S = 4 A, V _{GS} = 0 V		-	-	1.2	V
Reverse Recovery Time	t _{rr}	$T_{J} = 25 \text{ °C}, I_{F} = I_{S} = 4 \text{ A},$ dl/dt = 100 A/µs, V _R = 20 V		-	308	-	ns
Reverse Recovery Charge	Q _{rr}			-	1.8	-	μC
Reverse Recovery Current	I _{RRM}			-	11	-	A

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature.

b. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .

c. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .



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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

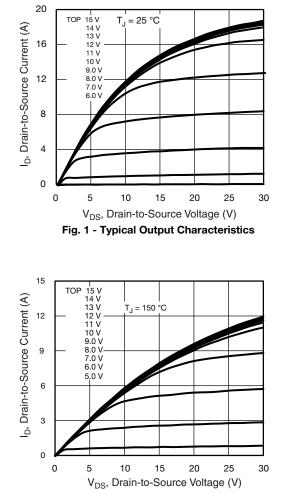
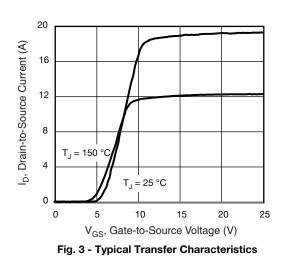


Fig. 2 - Typical Output Characteristics



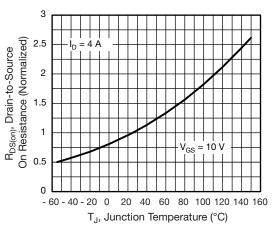


Fig. 4 - Normalized On-Resistance vs. Temperature

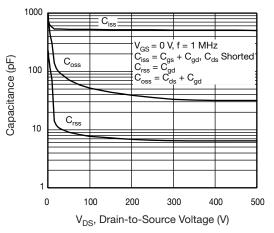
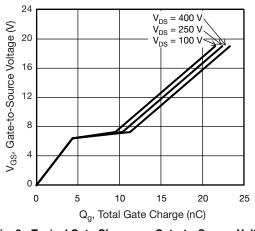


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage





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3 For technical questions, contact: <u>hvm@vishay.com</u> Document Number: 91488

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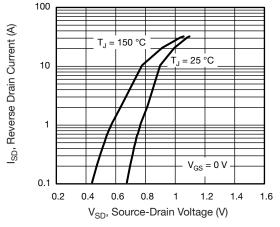


Fig. 7 - Typical Source-Drain Diode Forward Voltage

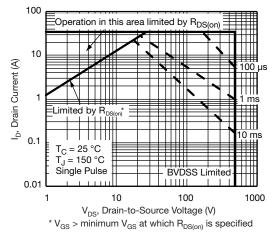


Fig. 8 - Maximum Safe Operating Area

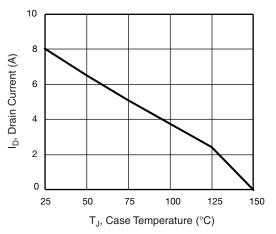


Fig. 9 - Maximum Drain Current vs. Case Temperature

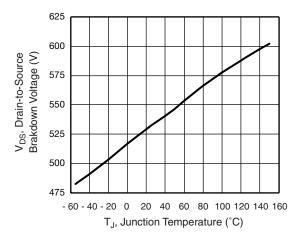
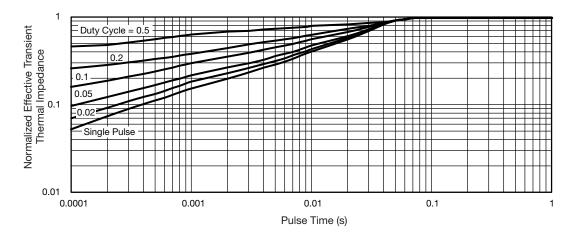
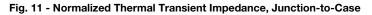


Fig. 10 - Typical Drain-to-Source Voltage vs. Temperature





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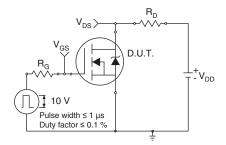


Fig. 12 - Switching Time Test Circuit

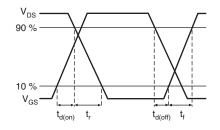


Fig. 13 - Switching Time Waveforms

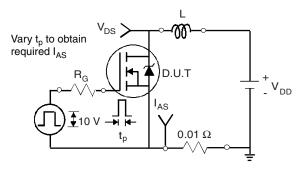


Fig. 14 - Unclamped Inductive Test Circuit

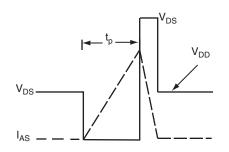


Fig. 15 - Unclamped Inductive Waveforms

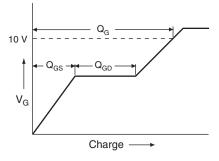


Fig. 16 - Basic Gate Charge Waveform

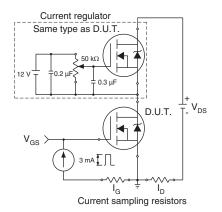
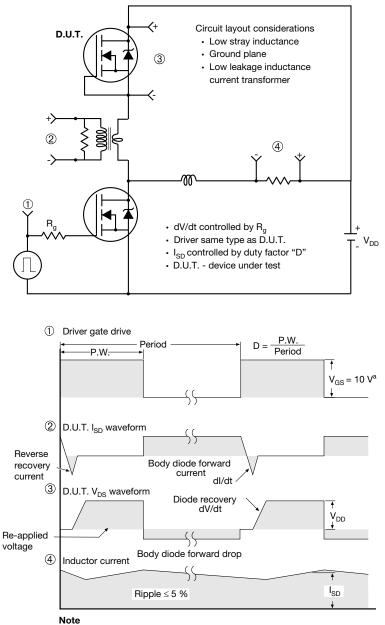


Fig. 17 - Gate Charge Test Circuit







a. $V_{GS} = 5 V$ for logic level devices

Fig. 18 - For N-Channel

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